

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

e patent application of

. Kata et al.

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Serial No.: 08/533,207

Group Art Unit: 2503

GROUP 2500

Filed: September 25, 1995

Examiner: M. Prenty

PROCESS FOR MANUFACTURING SEMICONDUCTOR DEVICE

AND SEMICONDUCTOR WAFER

Assistant Commissioner of Patents Washington, D.C. 20231

EXCESS CLAIM FEE PAYMENT LETTER

Submitted herewith is an Amendment Under 37 C.F.R. §1.111. After entry of the Amendment, the Government filing fee is calculated as follows:

> (Now) (Previously Paid)

20 = 0 x \$22 =\$_0.00 Total claims 20 Independent claims 5 3 = 2 x \$82 =\$_164.00

> TOTAL FEE \$ 164.00

A check for the statutory fee of \$164.00 is attached. You are also directed and authorized to charge or credit any difference or overpayment to Deposit Account No. 23-1951. A duplicate copy of this transmittal letter is attached.

Respectfully submitted,

Date: 12/19/97

Frederick W. Gibb, III

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